

SIMULATION OF EXASCALE NODES THROUGH RUNTIME HARDWARE MONITORING

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Heterogeneous Cores



Composition? Size? Speed?

Stacked Memories



Useful? Compute/BW Ratio? Latency? Capacity? Non-Volatile?

Heterogeneous Cores



Composition? Size? Speed?

Stacked Memories



Capacity? Non-Volatile?

Composition? Size? Speed?

Display DP TH / PLL HDMM

Heterogeneous Cores

GMC

GPU

DDR3 Controller

L2

Cache

Dual

Core x86

Module

UNB

PCIe ®

L2

Cache

Dual

Core

x86 Module

Thermal Constraints



Power Sharing? Heat dissipation? Sprinting?

Stacked Memories



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Software Co-Design

<pre>Real_t vol = volo[i]*vnew[i] ;</pre>	
<pre>Real_t norm = (Real_t)(1.0) / (<u>vol</u> + <u>ptiny</u>) ;</pre>	
Real_t dxj = (Real_t) (-0.25) * (SUM4 (x0, x1, x5, x4) - SUM4 (x3, x2, x6, x7))	1
Real_t dvj = (Real_t) (-0.25) * (SUM4(y0,y1,y5,y4) - SUM4(y3,y2,y6,y7)	1
Real_t dzj = (Real_t) (-0.25) * (SUM4(z0,z1,z5,z4) - SUM4(z3,z2,z6,z7)	
Real_t dxi = (Real_t) (0.25) * (SUM4(x1,x2,x6,x5) - SUM4(x0,x3,x7,x4)	1
Real_t dyi = (Real_t) (0.25) * (SUM4(y1, y2, y6, y5) - SUM4(y0, y3, y7, y4)	1.1
Real t dzi = (Real t) (0.25)*(SUM4(z1,z2,z6,z5) - SUM4(z0,z3,z7,z4)	. ;
Real t dxk = (Real t) (0.25) * (SUM4(x4,x5,x6,x7) - SUM4(x0,x1,x2,x3)	;
Real t dyk = (Real t) (0.25)*(SUM4(y4,y5,y6,y7) - SUM4(y0,y1,y2,y3)	. ;
Real t dzk = (Real t) (0.25) * (SUM4(z4,z5,z6,z7) - SUM4(z0,z1,z2,z3)	;
	· ·

New algorithms? Data placement? Programming models?

Heterogeneous Cores



Stacked Memories



Com

Exascale: Huge Design Space to Explore



Power Sharing? Heat dissipation? Sprinting? Real_t yol = yolo[i]*ynew[i] ; Real_t norm = (Real_t)(1.0) / (yol + ptiny) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(x0,x1,x5,x4) - SUM4(x3,x2,x6,x7)) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(y0,y1,y5,y4) - SUM4(y3,y2,y6,y7)) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(z0,z1,z5,z4) - SUM4(z3,z2,z6,z7)) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(x1,x2,x6,x5) - SUM4(z3,z2,z6,z7)) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(x1,x2,x6,x5) - SUM4(x0,x3,x7,x4)) ; Real_t dxi = (Real_t)(-0.25)*(SUM4(y1,y2,y6,y5) - SUM4(y0,y3,y7,y4)) ; Real_t dzi = (Real_t)(-0.25)*(SUM4(z1,z2,z6,z5) - SUM4(z0,z3,z7,z4)) ; Real_t dzi = (Real_t)(-0.25)*(SUM4(x4,x5,x6,x7) - SUM4(x0,x1,x2,x3)) ;

```
Real_t dxx = (Real_t) ( 0.25)*(SUM4(x4,x5,x6,x7) = SUM4(x0,x1,x2,x3));
Real_t dxx = (Real_t) ( 0.25)*(SUM4(y4,y5,y6,y7) = SUM4(y0,y1,y2,y3));
Real_t dxx = (Real_t) ( 0.25)*(SUM4(z4,z5,z6,z7) = SUM4(z0,z1,z2,z3));
```

New algorithms? Data placement? Programming models?



Power and Thermals on a real heterogeneous processor:



~2.5 trillion CPU instructions, ~60 trillion GPU operations



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Exascale Proxy Applications are Large

- Large initialization phases, many long iterations
- Not microbenchmarks
- Already reduced inputs and computation from real HPC applications



Power and Thermals on a real heterogeneous processor:



Exascale: Huge Execution Times

- Exascale Proxy Applications are Large
 - Large initialization phases, many long iterations
 - Not microbenchmarks
 - Already reduced inputs and computation from real HPC applications

EXISTING SIMULATORS

Microarchitecture Sims: e.g. gem5, Multi2Sim, MARSSx86, SESC, GPGPU-Sim

- Excellent for low-level details. We need these!
- Too slow for design space explorations: ~60 trillion operations = 1 year of sim time

▲ Functional Simulators: e.g. SimNow, Simics, QEMU, etc.

- Faster than microarchitectural simulators, good for things like access patterns
- No relation to hardware performance

High-Level Simulators: e.g. Sniper, Graphite, CPR

- Break operations down into timing models, e.g. core interactions, pipeline stalls, etc.
- Faster, easier to parallelize.
- Runtimes and complexity still constrained by desire to achieve accuracy.

TRADE OFF INDIVIDUAL TEST ACCURACY

Doctors do not start with:



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Fast Simulation Using Hardware Monitoring

HIGH-LEVEL SIMULATION METHODOLOGY MULTI-STAGE PERFORMANCE ESTIMATION PROCESS



BENEFITS OF MULTI-STEP PROCESS MANY DESIGN SPACE CHANGES ONLY NEED SECOND STEP





PERFORMANCE SCALING A SINGLE-THREADED APP Time Current Processor **End Time** Start Time Gather statistics and performance counters about: Instructions Committed, stall cycles • Memory operations, cache misses, etc. Power usage ۲ New Runtime **Analytical Performance** Scaling Model Simulated Processor

ANALYTIC PERFORMANCE SCALING

CPU Performance Scaling:

- Find stall events using HW perf. counters. Scale based on new machine parameters.
- Large amount of work in the literature on DVFS performance scaling, interval models..
- Some events can be scaled by fiat:
 "If IPC when not stalled on memory doubled, what would happen to performance?"

GPU Performance Scaling:

- Watch HW perf. counters that indicate work to do, memory usage, and GPU efficiency
- Scale values based on estimations of parameters to test

OTHER ANALYTIC MODELS

- Cache/Memory Access Model
 - Observe memory access traces using binary instrumentation or hardware
 - Send traces through high-level cache simulation system
 - Find knees in the curve, feed this back to CPU/GPU performance scaling model
- Power and thermal models
 - Power can be correlated to hardware events or directly measured
 - Scaled to future technology points
 - Any number of thermal models will work at this point
- Thermal and power models can feed into control algorithms that change system performance
 - This is **another** HW/SW co-design point. Fast operation is essential.

















MUST RECONSTRUCT CRITICAL PATHS

- ▲ Gather program-level relationship between individually scaled segments
- ▲ Use these happens-before relationships to build a legal execution order



- Gather ordering from library calls like pthread_create() and clWaitForEvents()
- Can also split segments based on program phases



Exascale node design space is huge

Trade off some accuracy for faster simulation

Use analytic models based on information from existing hardware

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Research Related Questions 4

MODSIM RELATED QUESTIONS

Major Contributions:

- A fast, high-level performance, power, and thermal analysis infrastructure
- Enables large design space exploration and HW/SW co-design with good feedback

Limitations:

- Trace-based simulation has known limitations w/r/t multiple paths of execution, wrong-path operations, etc.
- It can be difficult and slow to model something if your hardware can't measure values that are correlated to it.

Bigger Picture:

- Node-level performance model for datacenter/cluster performance modeling
- First pass model for APU power sharing algorithms.
- Exascale application co-design
- Complementary work to broad projects like SST

MODSIM RELATED QUESTIONS

- What is the one thing that would make it easier to leverage the results of other projects to further your own research
 - Theoretical bounds and analytic reasoning behind performance numbers. Even "good enough" guesses may help, vs. only giving the output of a simulator
- What are important thing to address in future work?
 - Better analytic scaling models. There are a lot in the literature, but many rely on simulation to propose new hardware that would gather correct statistics.
 - It would be great if open source performance monitoring software were better funded, had more people, etc.

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Backup **⊿**

▲ Is 3D-Stacked Memory Beneficial for Application X?

Baseline Performance Bandwidth Difference Latency Difference Thermal Model Core Changes due to Heat

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AN EXASCALE NODE EXAMPLE QUESTION

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